

Appl. No. 09/992,387
Amdt. dated December 20, 2004
Reply to Office action of Aug. 25, 2004

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

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1-24. (canceled)

25. (new) A device comprising:

an integrated circuit chip having a plurality of contact pads dimensioned smaller than 50 μm across and spaced apart less than 100 μm center to center;

a thin-film interposer having a single-layered insulating film;

substantially flat, electrically conductive lines disposed on only one side of the insulating film; electrically conductive paths extending through the interposer, contacting the conductive lines and forming exit ports on a second side of the insulating film; and

thermo-compressed electrical coupling members disposed between the contact pads and conductive lines, connecting the chip to the interposer.

26. (new) The device of claim 25, further comprising solder balls attached to the exit ports.

27. (new) The device of claim 25, further comprising encapsulating material encapsulating the integrated circuit chip.